SDFS019B - JANUARY 1989 - REVISED JANUARY 1997

 Package Options Include Plastic Small-Outline (D) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

description

These devices contain four independent 2-input exclusive-OR gates. They perform the Boolean function $Y = A \oplus B$ or $Y = \overline{AB} + A\overline{B}$ in positive logic.

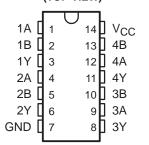
A common application is as a true/complement element. If one of the inputs is low, the other input is reproduced in true form at the output. If one of the inputs is high, the signal on the other input is reproduced inverted at the output.

The SN54F86 is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74F86 is characterized for operation from 0°C to 70°C.

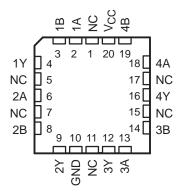
FUNCTION TABLE (each gate)

INP	UTS	OUTPUT
Α	В	Y
L	L	L
L	Н	н
Н	L	н
Н	Н	L

SN54F86...J PACKAGE SN74F86...D OR N PACKAGE (TOP VIEW)

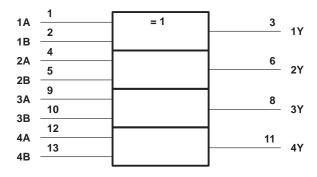


SN54F86 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the D, J, and N packages.



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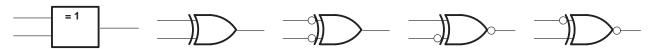


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exclusive-OR logic

An exclusive-OR gate has many applications, some of which can be represented better by alternative logic symbols.

EXCLUSIVE OR



These are five equivalent exclusive-OR symbols valid for an 'F86 gate in positive logic; negation may be shown at any two ports.

The output is active (low) if all inputs stand at the same logic level (i.e., A = B). EVEN-PARITY ELEMENT ODD-PARITY ELEMENT The output is active (low) if an even number of inputs (i.e., one 2) are active. The output is active (high) if an odd number of outputs (i.e., only 1 of the 2) are active.

absolute maximum rating	as over operatin	a free-air temp	erature range ((unless otherwise noted)†
	,	g • • • • • • • • • • • • • • • • •	, , , , , , , , , , , , , , , , , , , ,	(

Supply voltage range, V _{CC}	-0.5 V to 7 V
Input voltage range, V _I (see Note 1)	
Input current range	. –30 mA to 5 mA
Voltage range applied to any output in the high state	\dots -0.5 V to V _{CC}
Current into any output in the low state	40 mA
Package thermal impedance, θ _{JA} (see Note 2): D package	127°C/W
N package	
Storage temperature range, T _{Stg}	. −65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

			SN54F86		9	N74F86		UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.8			0.8	V
lik	Input clamp current			-18			-18	mA
ІОН	High-level output current			-1			-1	mA
l _{OL}	Low-level output current			20			20	mA
T _A	Operating free-air temperature	-55		125	0		70	°C



NOTES: 1. The input voltage ratings may be exceeded provided the input current ratings are observed.

^{2.} The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	,	SN54F86			UNIT		
PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	MIN	TYP†	MAX	UNII
VIK	$V_{CC} = 4.5 \text{ V},$	$I_I = -18 \text{ mA}$			-1.2			-1.2	V
Va.,	$V_{CC} = 4.5 \text{ V},$	I _{OH} = -1 mA	2.5	3.4		2.5	3.4		V
VOH	$V_{CC} = 4.75 \text{ V},$	I _{OH} = -1 mA				2.7			V
V _{OL}	$V_{CC} = 4.5 \text{ V},$	I _{OL} = 20 mA		0.3	0.5		0.3	0.5	V
Ι _Ι	$V_{CC} = 5.5 \text{ V},$	V _I = 7 V			0.1			0.1	mA
lіН	$V_{CC} = 5.5 \text{ V},$	V _I = 2.7 V			20			20	μΑ
I _{IL}	$V_{CC} = 5.5 \text{ V},$	V _I = 0.5 V			- 0.6			- 0.6	mA
los [‡]	$V_{CC} = 5.5 \text{ V},$	V _O = 0	-60		-150	-60		-150	mA
Іссн	$V_{CC} = 5.5 \text{ V},$	See Note 3		15	23		15	23	mA
ICCL	$V_{CC} = 5.5 \text{ V},$	V _I = 4.5 V		18	28		18	28	mA

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	C _I R _I	CC = 5 V L = 50 pl L = 500 s A = 25°C	F, Ω ,	C _L R _L	= 50 pF = 500Ω			UNIT
				′F86		SN54	IF86	SN74	F86	
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{PLH}	A or B	V	3	4	5.5	3	7	3	6.5	
t _{PHL}	(other input low)	ī	3	4.2	5.5	2.6	8	3	6.5	ns
t _{PLH}	A or B	V	3.5	5.3	7	3.5	10	3.5	8	ns
t _{PHL}	(other input high)	·	3	4.7	6.5	3	8	3	7.5	115

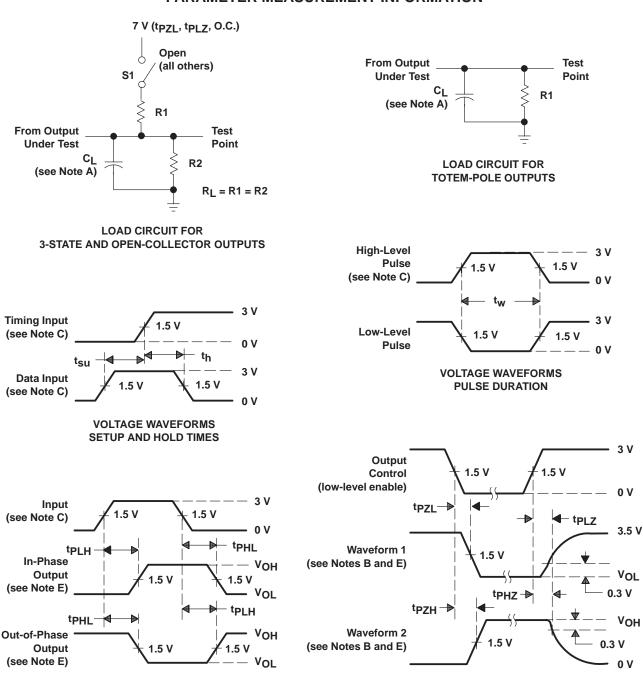
[§] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



[‡] Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

NOTE 3: I_{CCH} is measured with outputs open, and the A or B input (not both) at 4.5 V. Remaining inputs are grounded.

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

VOLTAGE WAVEFORMS

PROPAGATION DELAY TIMES (see Note D)

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: $PRR \le 1 \text{ MHz}$, $t_r = t_f \le 2.5 \text{ ns}$, duty cycle = 50%.

VOLTAGE WAVEFORMS

ENABLE AND DISABLE TIMES, 3-STATE OUTPUTS

- D. When measuring propagation delay times of 3-state outputs, switch S1 is open.
- E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms









PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Packag Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74F86D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74F86DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74F86DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74F86DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74F86DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74F86DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74F86N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74F86NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74F86NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74F86NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74F86NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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PACKAGE OPTION ADDENDUM

18-Sep-2008

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to Customer on an annual basis.	



TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

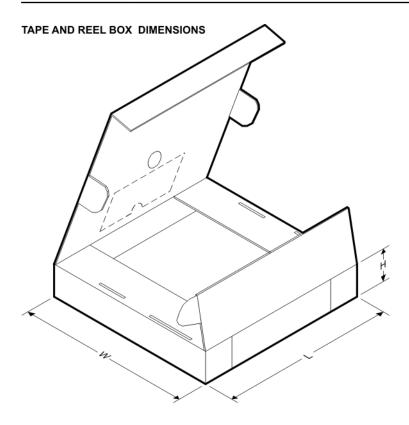
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74F86DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74F86NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1





*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74F86DR	SOIC	D	14	2500	346.0	346.0	33.0
SN74F86NSR	SO	NS	14	2000	346.0	346.0	33.0

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